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PRESS RELEASE

BE Semiconductor Industries Announces Interim Sales and Order Update and Operational Restructuring

Duiven, the Netherlands, June 18, 2007 - BE Semiconductor Industries N.V. ("the Company" or "BesI") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, today announced that based on preliminary estimates, it anticipates that its revenue and orders for the second quarter of 2007 will be approximately 5% and 10-15% below its respective revenue and orders for the first quarter of 2007. It also announced an operational restructuring focused on the consolidation of certain global manufacturing and sales and service activities in order to streamline its operations, reduce subsidiary overhead and improve profitability. The new organization structure will also facilitate the adoption of common system platforms offering the potential to significantly improve BesI's operating efficiency and working capital management in the future.

BesI estimates that the anticipated revenue shortfall versus the first quarter of 2007 and guidance for the second quarter of 2007 is due primarily to delays in customer acceptance of certain RFID system orders. The Company believes that the order shortfall versus levels achieved in the first quarter of 2007 is due primarily to lower than anticipated orders for its die sorting systems and, to a lesser extent, lower orders for singulation and RFID plating systems as a result of demand for assembly equipment that is generally softer than previously anticipated. Guidance for the second quarter of 2007 was for orders to be flat to up 5% versus the first quarter of 2007.

One component of the restructuring involves the net reduction of approximately 35 employees in the Netherlands (of whom 16 are fixed contract employees), approximately 40 employees in the US and approximately 10 employees in other regions. In total, the work force reduction represents approximately 7% of BesI's worldwide fixed headcount at March 31, 2007. At present, BesI anticipates that it will incur charges not exceeding approximately €5 million in connection with the restructuring of which approximately €3 million is anticipated to be recorded in the second quarter of 2007 and the remainder of which is expected to be incurred during the third and fourth quarters of 2007. Of the total anticipated charges, the Company estimates that (i) approximately €3.3 million relates to severance and social charges involved in the proposed workforce reduction as well as lease termination costs and legal/advisory fees in connection with the restructuring, (ii) approximately €0.9 million relates primarily to the write-off of inventory in connection with the common platform initiative at Fico Netherlands and Fico Asia and the transfer of inventory and

production activities between Datacon and Laurier and (iii) approximately € 0.8 million relates to the write-off of patents and trademarks at Laurier in connection with an evaluation of its current product portfolio. The personnel terminations and production transfer contemplated by the restructuring are anticipated to occur primarily during the second half of 2007.

The Company anticipates that the restructuring will generate potential annual pre tax cost savings of approximately € 6 million commencing in 2008. However, the combination of charges related to the restructuring and the Company's anticipated revenue shortfall in the second quarter of 2007 will result in Besl's incurring a net loss for the quarter.

The restructuring plan involves principally three operating activities: 1) the integration of Besl's Laurier subsidiary, located in Londonderry, New Hampshire, USA with its Datacon subsidiary, located in Radfeld, Austria, 2) the consolidation of all Besl's packaging equipment product activities and 3) the consolidation and integration of all sales and customer support services for die bonding, die sorting and packaging equipment products in one global organization. In addition, as part of the streamlining process, the Company will seek to develop common system platforms for its Datacon die bonding/sorting products and its Fico packaging equipment products in order to better standardize production across its various assembly operations. In this manner, management hopes to achieve incremental process, cost, purchasing and working capital efficiencies which should serve to reduce subsidiary overhead and inventory levels and expedite delivery times to customers.

As part of the restructuring, Besl will integrate the operations of its Laurier and Datacon subsidiaries in the second half of 2007 wherein all Laurier die sorting products will continue to be supported under the Datacon brand name. It is anticipated that Laurier's Londonderry, New Hampshire facility will be maintained and that remaining personnel will support and advance research and development and customer service functions for Besl die sorting and vision products. At present, it is contemplated that all current die sorting production activities will be transferred to Datacon's Radfeld, Austria facility or Besl's Malaysian manufacturing operations.

The restructuring of Besl's packaging equipment operations involves the consolidation and integration of its Fico molding, trim and form and singulation equipment units at its facility in Duiven, the Netherlands. It is contemplated that design, engineering, development and business management functions of these three units will be consolidated under one management structure in order to simplify product design and decision making and reduce subsidiary overhead.

The re-organization of the Company's sales and customer support activities focuses on the integration of sales and marketing activities for each of its die sorting, die bonding and packaging equipment systems whereby sales and customer support personnel and offices will be consolidated worldwide through the establishment of global Besl sales and customer support organizations. As a result, redundant sales and support overhead can be reduced and the Company's management structure can be greatly simplified.



In commenting on the announcement, President and Chief Executive Officer Richard W. Blickman noted: "We are disappointed with our estimated shortfall in revenue and orders versus guidance for the second quarter of 2007. This disappointment relates primarily to orders for our die sorting, singulation and RFID plating systems and points to pockets of weakness in the assembly equipment market currently. However, our principal die bonding and packaging equipment sales and orders are still on track to meet expectations for the second quarter.

In addition, by means of the restructuring we have positioned Besic so that it can realize its profit objectives in a highly cyclical and ever changing semiconductor equipment landscape. The management board believes that the best manner to achieve our targets at present is to centralize certain management functions and to reduce redundant production and administrative overhead wherever possible in our global operations. By these measures, we ultimately hope to achieve an integrated and streamlined global organization structure under the Besic umbrella while maintaining the separate integrity and quality of our Datacon, Fico and Mecoc equipment brands. We also believe that the adoption of common system platforms by our die handling and packaging equipment operations holds the potential to significantly improve Besic's operating efficiency and working capital management in the future."

The Company expects to report second quarter and half year 2007 results on July 26, 2007.

About BE Semiconductor Industries N.V.

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European, Asian, Korean and Japanese semiconductor manufacturers and subcontractors which utilize its products for both array connect and conventional leadframe manufacturing processes. For more information about Besic, please visit our website at www.besic.com.

Caution Concerning Forward Looking Statements

This press release contains forward-looking statements, which are found in various places throughout the press release. The words "anticipate", "estimate", "expect", "can", "intend", "believes", "may", "plan", "predict", "project", "forecast", "will", "would", and similar expressions are intended to identify forward looking statements, although not all forward looking statements contain these identifying words. While these forward looking statements represent our judgments and future expectations concerning the development of our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from our expectations. These factors include, but are not limited to, those listed or discussed in Besic's Annual Report for the year ended December 31, 2006, as well as the risk that anticipated orders may not materialize or that orders received may be postponed or canceled, generally without charges; the volatility in the demand for semiconductors and our products and services; acts of terrorism and violence; overall global economic conditions; risks, such as changes in trade regulations, currency fluctuations, political instability and war, associated with substantial foreign

customers, suppliers and foreign manufacturing operations; potential instability in foreign capital markets; the risk of failure to successfully manage our expanding and more diverse operations; and other key factors that could adversely affect our businesses and financial performance contained in our filings and reports, including our statutory consolidated statements. We are under no obligation to (and expressly disclaim any such obligation to) update or alter our forward-looking statements whether as a result of new information, future events or otherwise.

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